



TEC™ 044/2

Multipurpose primer for indoor applications

ADVANTAGES

- Multipurpose primer for absorbing and non absorbing subfloors
- Application on wall and floor.
- Suitable for use over underfloor heating systems
- Solvent-free, very low emissions of VOC (emicode EC1 Plus)



USE

- Improving the adhesion of self levelling compounds on porous substrate like concrete slab cement-based screed, calcium sulphate based screed...
- Improving the adhesion of self levelling compounds non absorbing subfloors like ceramics tiles, stone floors...
- Improving the adhesion on wooden floors or old, fixed and water-resistant adhesive residues
- To be used prior self-leveling compound application or prior to direct application of an acrylic waterbased adhesive on even standard subfloors
- For more detailed informations on possible applications, please contact our technical assistance service

GENERAL CHARACTERISTICS

Basis	aqueous dispersion of synthetic resins
Color	white
Application tool	Foam roller
Consumption	100-200 g/m ² depending on substrate and type of floor covering
Drying time	1 hour on absorbing cement-based subfloor 4 to 6 hours on non-absorbing subfloor 12 to 24 hours on calcium sulfate based screed
Installation temperature	> +10°C
Packaging	10 kg and 5 kg jerricans
Frost Sensitivity	yes
Shelf life	12 months if unopened and stored in a dry area at normal temperature
Cleaning agent	Water
Safety Data Sheet	Available on demand.

Above-mentioned laboratory values should be used as an indication that should be adapted depending on installation conditions (substrate absorption, temperature, hygrometry...)

SUBSTRATES

- The substrate must be sound, solid, thoroughly clean, permanently dry and free of oil, wax, grease and any contaminant that might act as a bond breaker.
- The substrates must conform to the norms and regulatory texts (DTU, CPT etc) .Take every necessary measure in case of deficiency.
- Control joints and cracks need to be closed professionally (e.g.: by using our TEC™ 817 epoxy cartridge + TEC™ 846)
- Wood subfloors must be securely fastened with screw type or ring shank nails and adhesive.
- For concrete slabs and cement-based screed which are not dry and/or which are subject to moisture migration, use our epoxy primer TEC™ 024 MVB, according to its technical data sheet.
- Do not use TEC™ 044/2 for moisture sensitive types of subfloors e.g. stone wood, magnesia screed and water soluble adhesives residues
- All friable, non adhesive residues must be mechanically cleaned down to a sound, solid surface by shot blasting, scarifying or similar.
- Elimination (by vacuuming) of all dusts.

Nota : Please refer to the technical data sheet of the surface preparation products

CONDITIONS OF USE

Temperatures to be heeded during use	Application should not be carried out during periods of frost or intense heat The ambient temperature (<i>ideal</i>) must be between +15 and +25°C Application should not be carried out on a floor in the process of heating. Heating is suspended for a minimum of 48 hours before application
Minimum usage temperature	Substrate and atmospheric temperatures must be at least equal to +10°C.
Maximum permissible humidity	Ambient humidity and the substrate temperature must be such that there is no condensation at substrate level (<i>dew point</i>).

APPLICATION

- Stirr well before use
- The primer is to be equally applied onto the subfloor with a foam roller. Avoid the formation of puddles.
- The drying time depends on the consumption, the room temperature, the air humidity and the type of subsequently applied material.
- Always wait for the complete drying of the primer film before applying the self levelling compound or glue.
- Fresh spilled adhesive needs to be removed with water immediately.
- Do not walk on the floor during drying time.

Recommendation:

All work must be carried out in compliance with DTU, CPT, professional regulations, etc. in force, according to the respective technical data sheets for our products, whilst complying with the laying instructions from the covering manufacturer, recommended by the application guide, technical data sheets and other documents.